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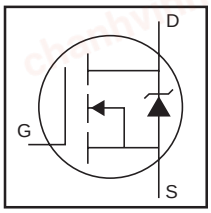
International
IOR Rectifier

PD - 14275D

# IRFB4310PbF
# IRFS4310PbF
# IRFSL4310PbF

HEXFET® Power MOSFET

### Applications
- High Efficiency Synchronous Rectification in SMPS
- Uninterruptible Power Supply
- High Speed Power Switching
- Hard Switched and High Frequency Circuits




| | |
|---|---|
| $V_{DSS}$ | 100V |
| $R_{DS(on)}$ typ. | 5.6mΩ |
| max. | 7.0mΩ |
| $I_D$ | 130A |

### Benefits
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche SOA
- Enhanced body diode dV/dt and dI/dt Capability
- Lead-Free




TO-220AB
IRFB4310PbF




D²Pak
IRFS4310PbF




TO-262
IRFSL4310PbF

## Absolute Maximum Ratings

| Symbol | Parameter | Max. | Units |
|---|---|---|---|
| $I_D$ @ $T_C$ = 25°C | Continuous Drain Current, $V_{GS}$ @ 10V | 130① | A |
| $I_D$ @ $T_C$ = 100°C | Continuous Drain Current, $V_{GS}$ @ 10V | 92① | |
| $I_{DM}$ | Pulsed Drain Current ② | 550 | |
| $P_D$ @$T_C$ = 25°C | Maximum Power Dissipation | 300 | W |
| | Linear Derating Factor | 2.0 | W/°C |
| $V_{GS}$ | Gate-to-Source Voltage | ± 20 | V |
| dV/dt | Peak Diode Recovery ④ | 14 | V/ns |
| $T_J$<br>$T_{STG}$ | Operating Junction and<br>Storage Temperature Range | -55 to + 175 | °C |
| | Soldering Temperature, for 10 seconds<br>(1.6mm from case) | 300 | |
| | Mounting torque, 6-32 or M3 screw | 10lb·in (1.1N·m) | |

## Avalanche Characteristics

| | | | |
|---|---|---|---|
| $E_{AS\ (Thermally\ limited)}$ | Single Pulse Avalanche Energy ③ | 980 | mJ |
| $I_{AR}$ | Avalanche Current ① | See Fig. 14, 15, 22a, 22b, | A |
| $E_{AR}$ | Repetitive Avalanche Energy ⑤ | | mJ |

## Thermal Resistance

| Symbol | Parameter | Typ. | Max. | Units |
|---|---|---|---|---|
| $R_{\theta JC}$ | Junction-to-Case ⑨ | —— | 0.50 | °C/W |
| $R_{\theta CS}$ | Case-to-Sink, Flat Greased Surface , TO-220 | 0.50 | —— | |
| $R_{\theta JA}$ | Junction-to-Ambient, TO-220 ⑨ | —— | 62 | |
| $R_{\theta JA}$ | Junction-to-Ambient (PCB Mount) , D²Pak ⑧⑨ | —— | 40 | |

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## Static @ $T_J$ = 25°C (unless otherwise specified)

| Symbol | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---|---|---|---|---|---|---|
| $V_{(BR)DSS}$ | Drain-to-Source Breakdown Voltage | 100 | — | — | V | $V_{GS}$ = 0V, $I_D$ = 250µA |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient | — | 0.064 | — | V/°C | Reference to 25°C, $I_D$ = 1mA② |
| $R_{DS(on)}$ | Static Drain-to-Source On-Resistance | — | 5.6 | 7.0 | mΩ | $V_{GS}$ = 10V, $I_D$ = 75A ⑤ |
| $V_{GS(th)}$ | Gate Threshold Voltage | 2.0 | — | 4.0 | V | $V_{DS}$ = $V_{GS}$, $I_D$ = 250µA |
| $I_{DSS}$ | Drain-to-Source Leakage Current | — | — | 20 | µA | $V_{DS}$ = 100V, $V_{GS}$ = 0V |
| | | — | — | 250 | | $V_{DS}$ = 100V, $V_{GS}$ = 0V, $T_J$ = 125°C |
| $I_{GSS}$ | Gate-to-Source Forward Leakage | — | — | 200 | nA | $V_{GS}$ = 20V |
| | Gate-to-Source Reverse Leakage | — | — | -200 | | $V_{GS}$ = -20V |
| $R_G$ | Gate Input Resistance | — | 1.4 | — | Ω | f = 1MHz, open drain |

## Dynamic @ $T_J$ = 25°C (unless otherwise specified)

| Symbol | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---|---|---|---|---|---|---|
| gfs | Forward Transconductance | 160 | — | — | S | $V_{DS}$ = 50V, $I_D$ = 75A |
| $Q_g$ | Total Gate Charge | — | 170 | 250 | nC | $I_D$ = 75A |
| $Q_{gs}$ | Gate-to-Source Charge | — | 46 | — | | $V_{DS}$ = 80V |
| $Q_{gd}$ | Gate-to-Drain ("Miller") Charge | — | 62 | — | | $V_{GS}$ = 10V ⑤ |
| $t_{d(on)}$ | Turn-On Delay Time | — | 26 | — | ns | $V_{DD}$ = 65V |
| $t_r$ | Rise Time | — | 110 | — | | $I_D$ = 75A |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 68 | — | | $R_G$ = 2.6Ω |
| $t_f$ | Fall Time | — | 78 | — | | $V_{GS}$ = 10V ⑤ |
| $C_{iss}$ | Input Capacitance | — | 7670 | — | pF | $V_{GS}$ = 0V |
| $C_{oss}$ | Output Capacitance | — | 540 | — | | $V_{DS}$ = 50V |
| $C_{rss}$ | Reverse Transfer Capacitance | — | 280 | — | | $f$ = 1.0MHz |
| $C_{oss}$ eff. (ER) | Effective Output Capacitance (Energy Related)⑦ | — | 650 | — | | $V_{GS}$ = 0V, $V_{DS}$ = 0V to 80V ⑧, See Fig.11 |
| $C_{oss}$ eff. (TR) | Effective Output Capacitance (Time Related)⑥ | — | 720.1 | — | | $V_{GS}$ = 0V, $V_{DS}$ = 0V to 80V ⑥, See Fig. 5 |

## Diode Characteristics

| Symbol | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---|---|---|---|---|---|---|
| $I_S$ | Continuous Source Current (Body Diode) | — | — | 130① | A | MOSFET symbol showing the integral reverse p-n junction diode. |
| $I_{SM}$ | Pulsed Source Current (Body Diode) ②⑦ | — | — | 550 | | |
| $V_{SD}$ | Diode Forward Voltage | — | — | 1.3 | V | $T_J$ = 25°C, $I_S$ = 75A, $V_{GS}$ = 0V ⑤ |
| $t_{rr}$ | Reverse Recovery Time | — | 45 | 68 | ns | $T_J$ = 25°C $V_R$ = 85V, |
| | | — | 55 | 83 | | $T_J$ = 125°C $I_F$ = 75A |
| $Q_{rr}$ | Reverse Recovery Charge | — | 82 | 120 | nC | $T_J$ = 25°C di/dt = 100A/µs ⑤ |
| | | — | 120 | 180 | | $T_J$ = 125°C |
| $I_{RRM}$ | Reverse Recovery Current | — | 3.3 | — | A | $T_J$ = 25°C |
| $t_{on}$ | Forward Turn-On Time | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) | | | | |

**Notes:**

① Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A

② Repetitive rating; pulse width limited by max. junction temperature.

③ Limited by $T_{Jmax}$, starting $T_J$ = 25°C, L = 0.35mH $R_G$ = 25Ω, $I_{AS}$ = 75A, $V_{GS}$ =10V. Part not recommended for use above this value.

④ $I_{SD}$ ≤ 75A, di/dt ≤ 550A/µs, $V_{DD}$ ≤ $V_{(BR)DSS}$, $T_J$ ≤ 175°C.

⑤ Pulse width ≤ 400µs; duty cycle ≤ 2%.

⑥ $C_{oss}$ eff. (TR) is a fixed capacitance that gives the same charging time as $C_{oss}$ while $V_{DS}$ is rising from 0 to 80% $V_{DSS}$.

⑦ $C_{oss}$ eff. (ER) is a fixed capacitance that gives the same energy as $C_{oss}$ while $V_{DS}$ is rising from 0 to 80% $V_{DSS}$.

⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.

⑨ $R_\theta$ is measured at $T_J$ approximately 90°C.

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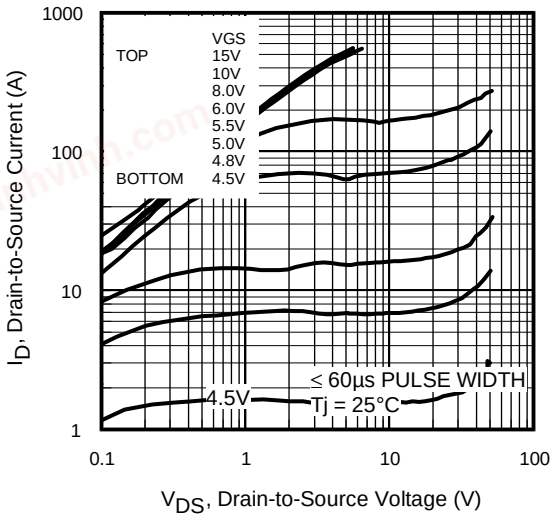



**Fig 1.** Typical Output Characteristics

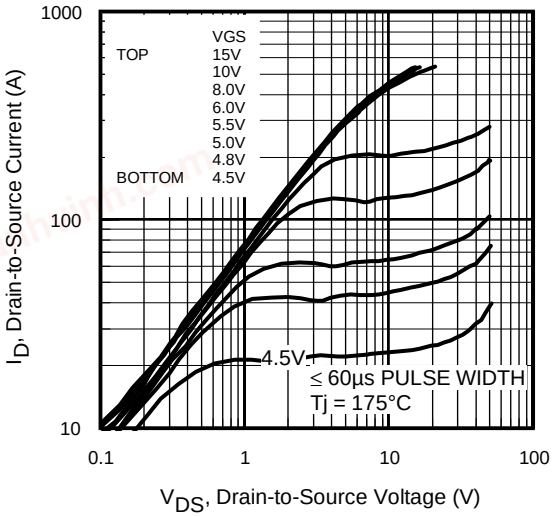



**Fig 2.** Typical Output Characteristics

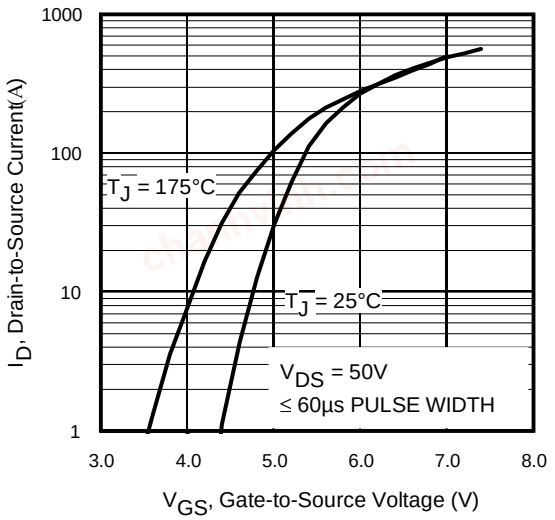



**Fig 3.** Typical Transfer Characteristics

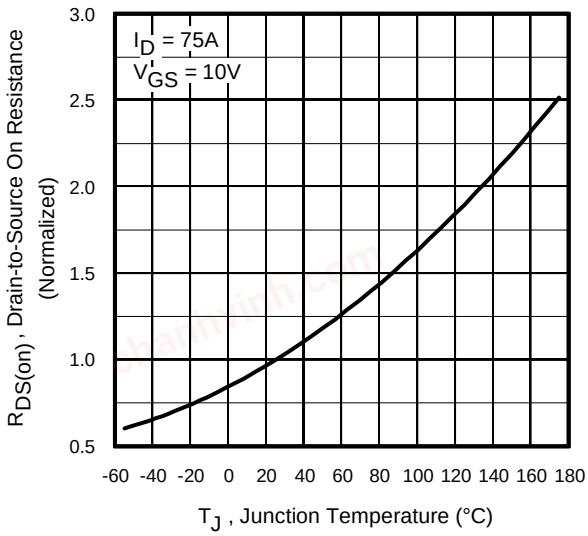



**Fig 4.** Normalized On-Resistance vs. Temperature

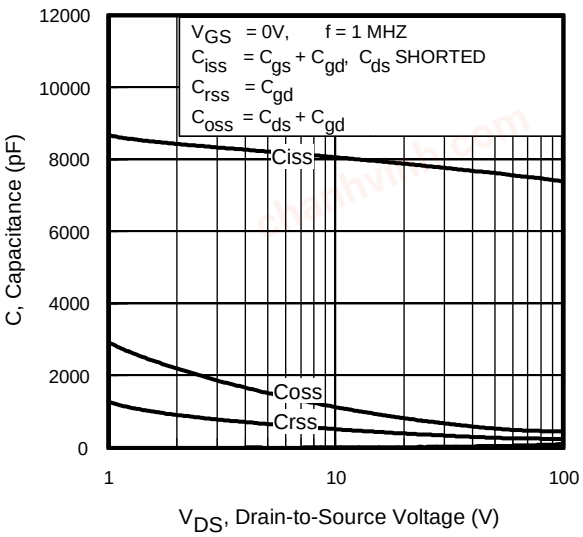



**Fig 5.** Typical Capacitance vs. Drain-to-Source Voltage

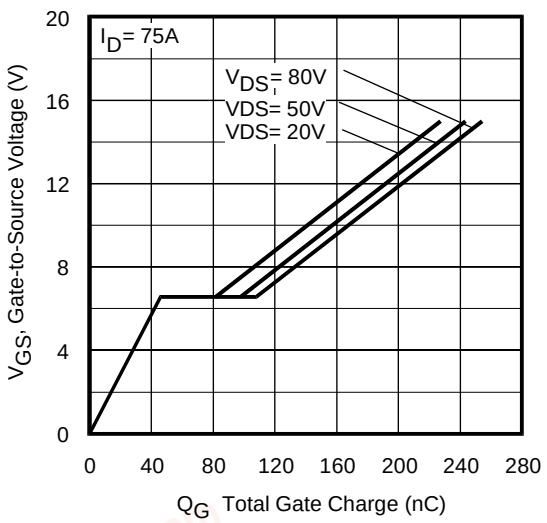



**Fig 6.** Typical Gate Charge vs. Gate-to-Source Voltage

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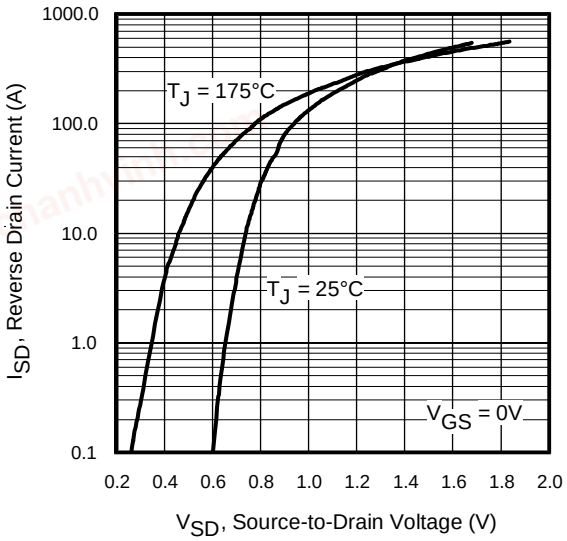



**Fig 7.** Typical Source-Drain Diode Forward Voltage

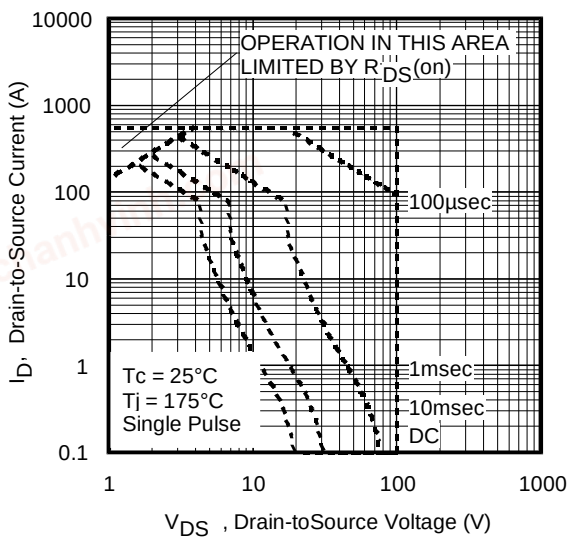



**Fig 8.** Maximum Safe Operating Area

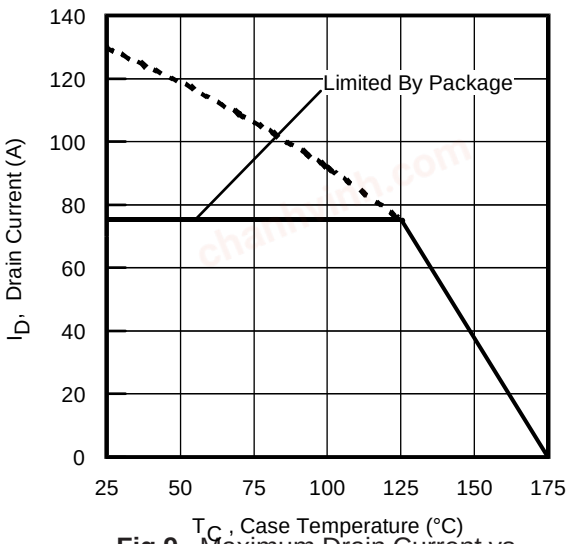



**Fig 9.** Maximum Drain Current vs. Case Temperature

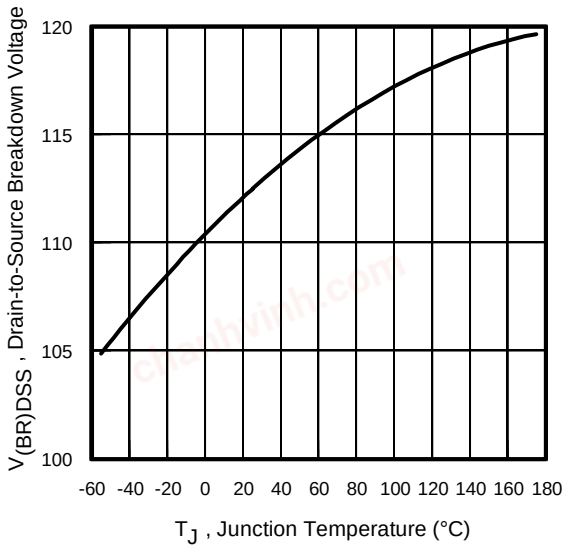



**Fig 10.** Drain-to-Source Breakdown Voltage

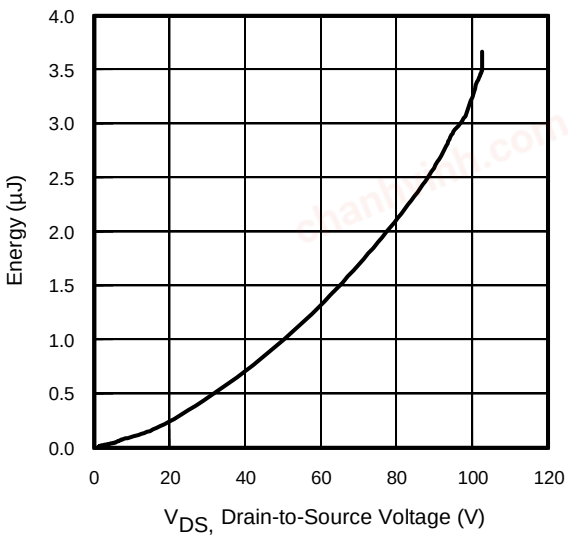



**Fig 11.** Typical $C_{OSS}$ Stored Energy

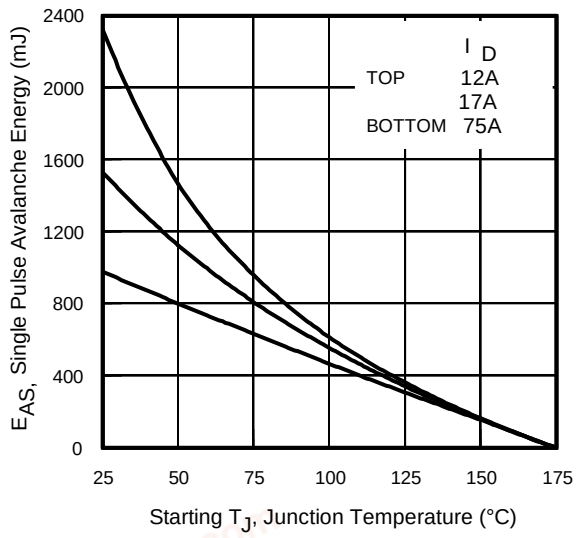



**Fig 12.** Maximum Avalanche Energy Vs. DrainCurrent

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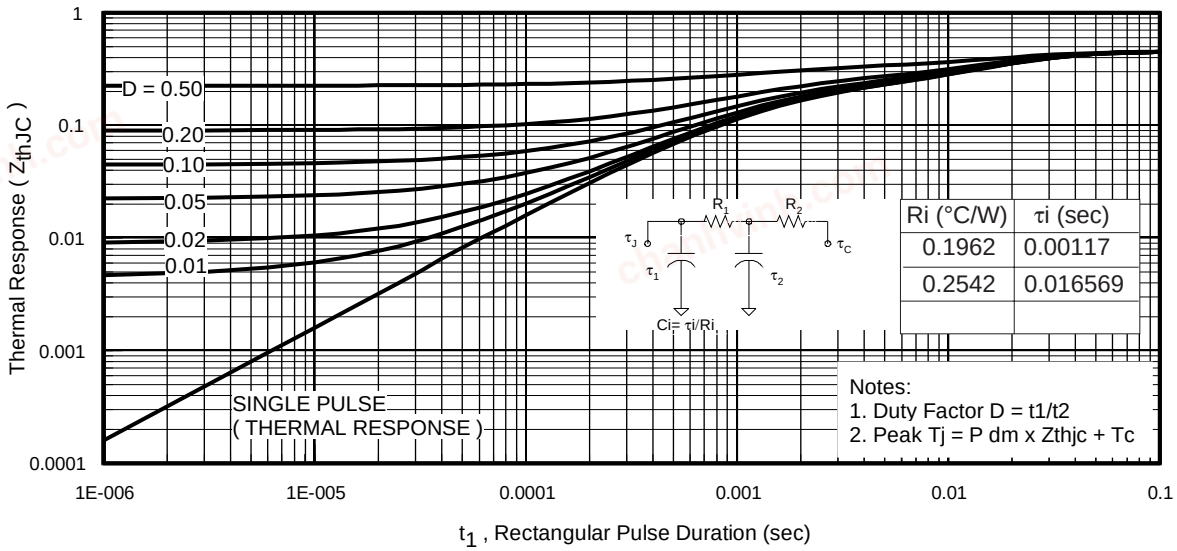



**Fig 13.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

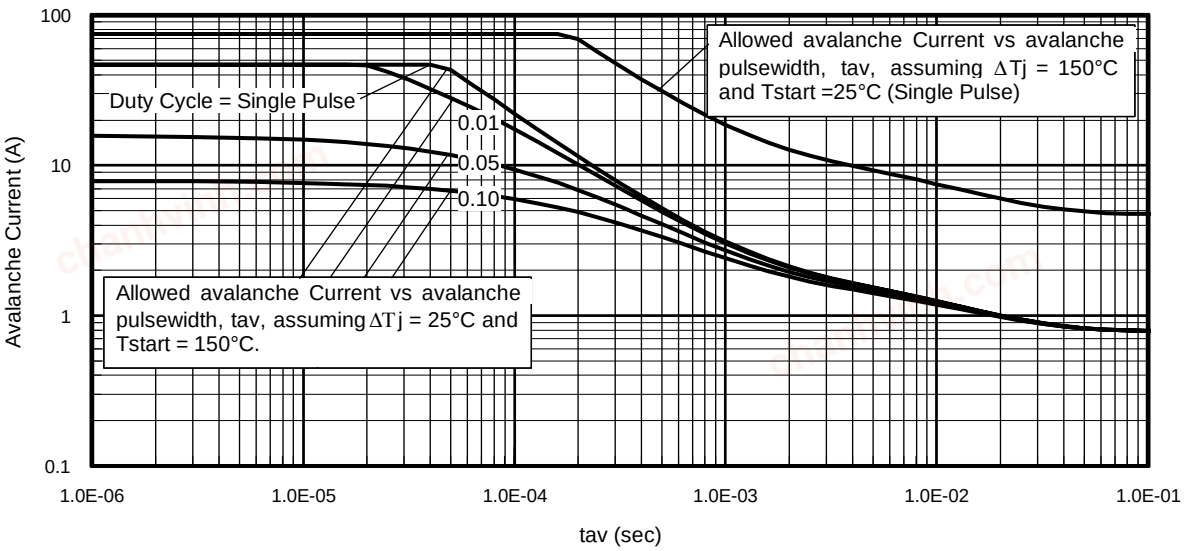



**Fig 14.** Typical Avalanche Current vs.Pulsewidth

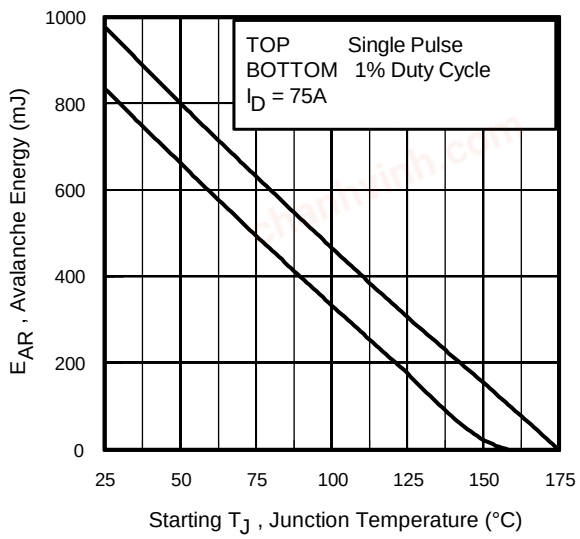



**Fig 15.** Maximum Avalanche Energy vs. Temperature

**Notes on Repetitive Avalanche Curves , Figures 14, 15:**
**(For further info, see AN-1005 at www.irf.com)**

1. Avalanche failures assumption:
   Purely a thermal phenomenon and failure occurs at a temperature far in excess of $T_{jmax}$. This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as neither $T_{jmax}$ nor $I_{av\ (max)}$ is exceeded.
3. Equation below based on circuit and waveforms shown in Figures 16a, 16b.
4. $P_{D\ (ave)}$ = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6. $I_{av}$ = Allowable avalanche current.
7. $\Delta T$ = Allowable rise in junction temperature, not to exceed $T_{jmax}$ (assumed as 25°C in Figure 14, 15).
   $t_{av}$ = Average time in avalanche.
   D = Duty cycle in avalanche = $t_{av} \cdot f$
   $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see Figures 13)

$$P_{D\ (ave)} = 1/2\ (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$
$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$
$$E_{AS\ (AR)} = P_{D\ (ave)} \cdot t_{av}$$

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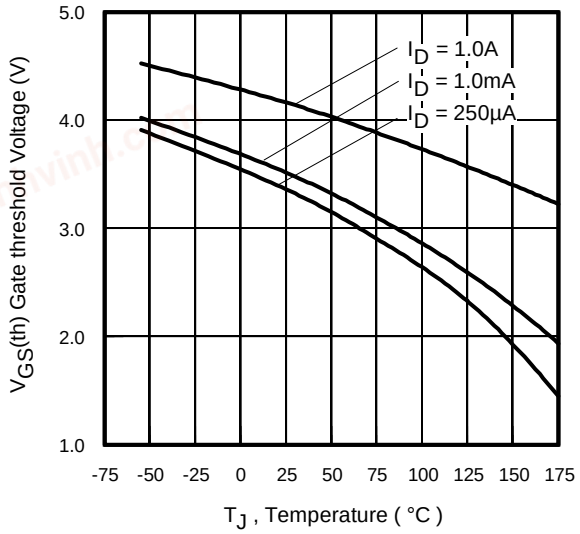



**Fig 16.** Threshold Voltage Vs. Temperature

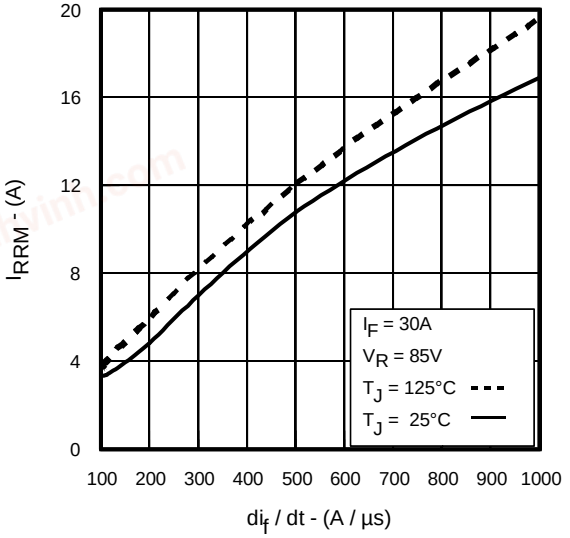



**Fig. 17** - Typical Recovery Current vs. $di_f/dt$

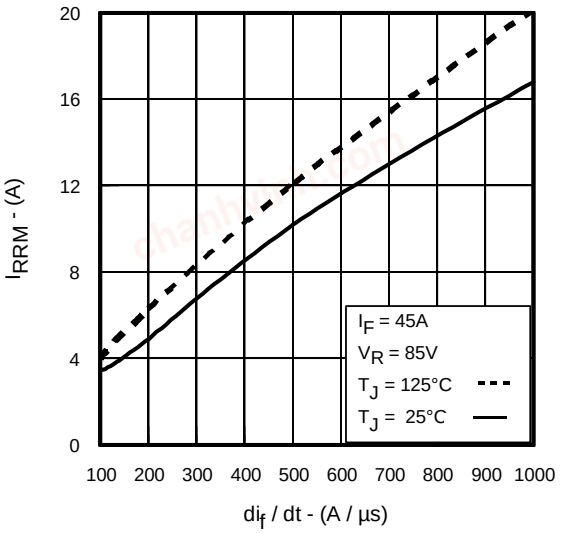



**Fig. 18** - Typical Recovery Current vs. $di_f/dt$

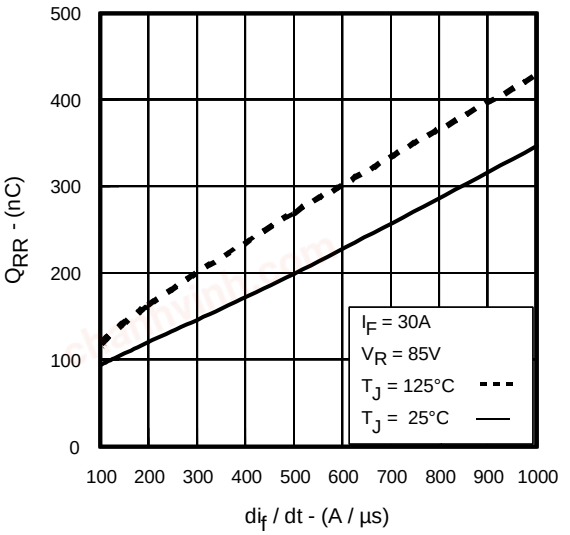



**Fig. 19** - Typical Stored Charge vs. $di_f/dt$

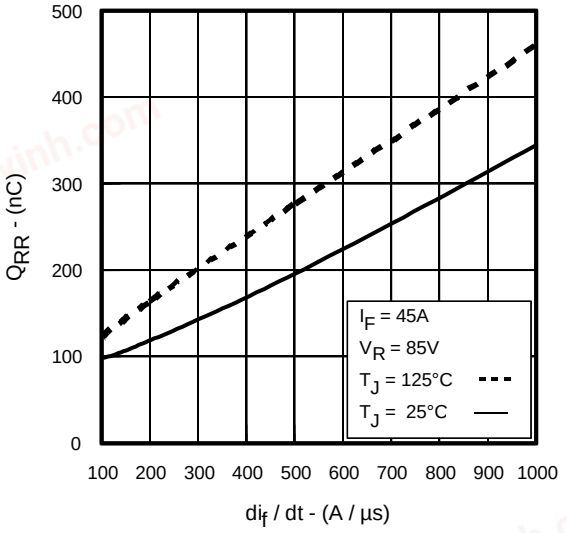



**Fig. 20** - Typical Stored Charge vs. $di_f/dt$

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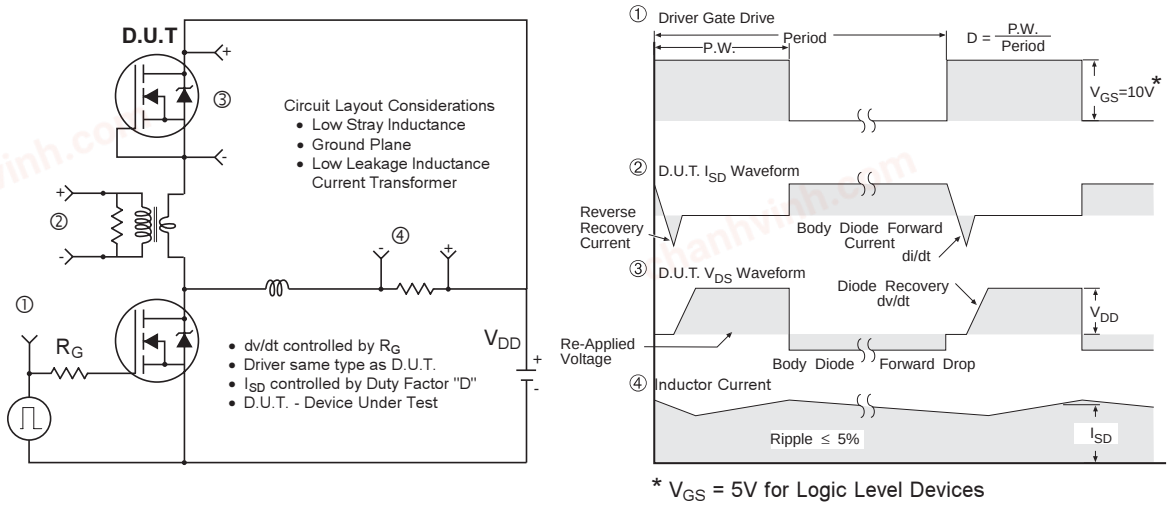



**Fig 21.** Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

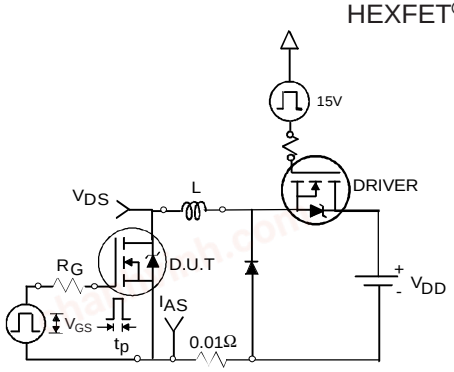



**Fig 22a.** Unclamped Inductive Test Circuit

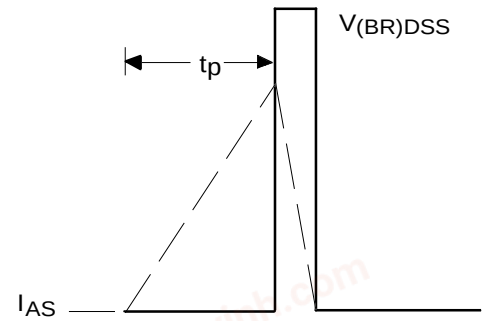



**Fig 22b.** Unclamped Inductive Waveforms

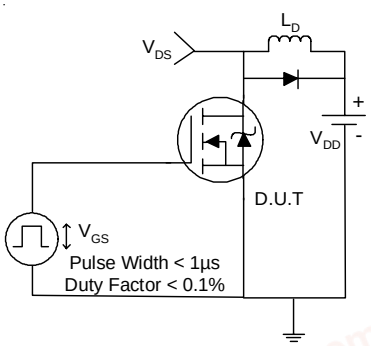



**Fig 23a.** Switching Time Test Circuit

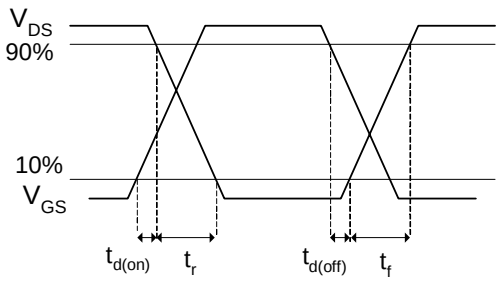



**Fig 23b.** Switching Time Waveforms

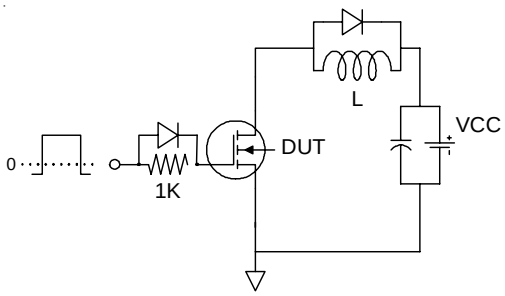



**Fig 24a.** Gate Charge Test Circuit

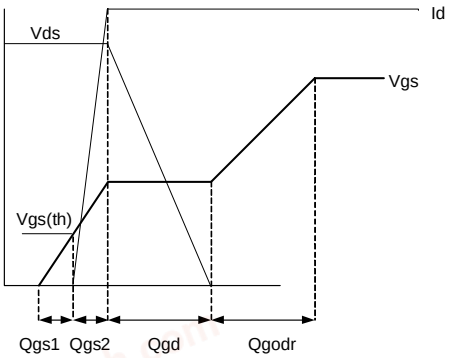


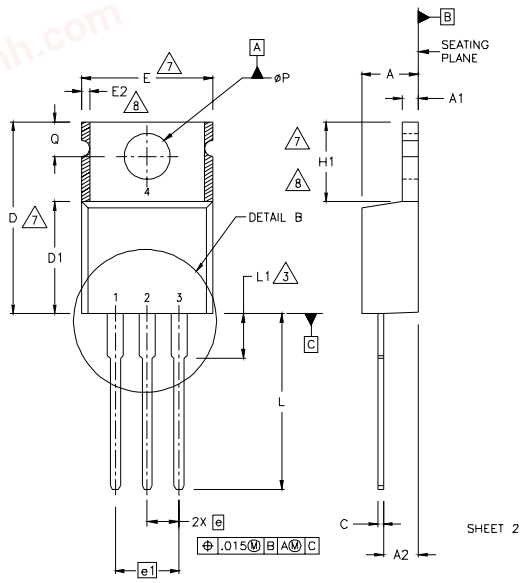

**Fig 24b.** Gate Charge Waveform

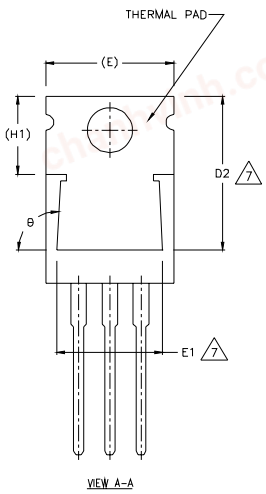
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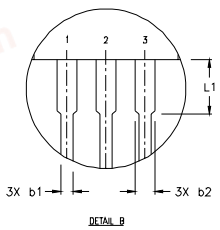


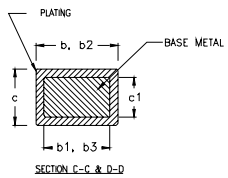
## TO-220AB Package Outline

Dimensions are shown in millimeters (inches)




NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
2. DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
3. LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. DIMENSION b1 & c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION : INCHES.
7. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
8. DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.

LEAD ASSIGNMENTS

HEXFET
1.- GATE
2.- DRAIN
3.- SOURCE

IGBTs, CoPACK
1.- GATE
2.- COLLECTOR
3.- EMITTER

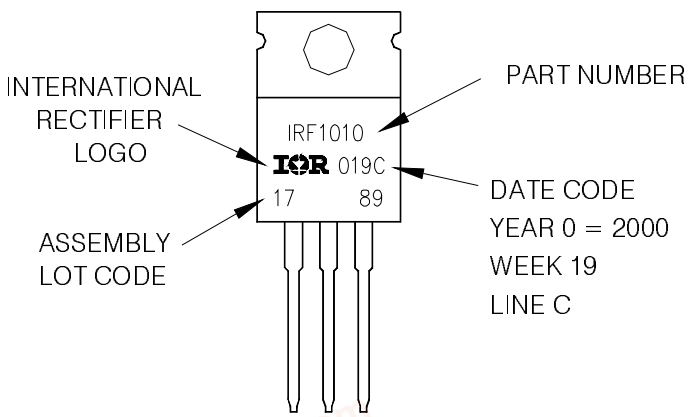
DIODES
1.- ANODE/OPEN
2.- CATHODE
3.- ANODE

| SYMBOL | DIMENSIONS | | | | NOTES |
|---|---|---|---|---|---|
| | MILLIMETERS | | INCHES | | |
| | MIN. | MAX. | MIN. | MAX. | |
| A | 3.56 | 4.82 | .140 | .190 | |
| A1 | 0.51 | 1.40 | .020 | .055 | |
| A2 | 2.04 | 2.92 | .080 | .115 | |
| b | 0.38 | 1.01 | .015 | .040 | |
| b1 | 0.38 | 0.96 | .015 | .038 | 5 |
| b2 | 1.15 | 1.77 | .045 | .070 | |
| b3 | 1.15 | 1.73 | .045 | .068 | |
| c | 0.36 | 0.61 | .014 | .024 | |
| c1 | 0.36 | 0.56 | .014 | .022 | 5 |
| D | 14.22 | 16.51 | .560 | .650 | 4 |
| D1 | 8.38 | 9.02 | .330 | .355 | |
| D2 | 12.19 | 12.88 | .480 | .507 | 7 |
| E | 9.66 | 10.66 | .380 | .420 | 4,7 |
| E1 | 8.38 | 8.89 | .330 | .350 | 7 |
| e | 2.54 BSC | | .100 BSC | | |
| e1 | 5.08 | | .200 BSC | | |
| H1 | 5.85 | 6.55 | .230 | .270 | 7,8 |
| L | 12.70 | 14.73 | .500 | .580 | |
| L1 | – | 6.35 | – | .250 | 3 |
| øP | 3.54 | 4.08 | .139 | .161 | |
| Q | 2.54 | 3.42 | .100 | .135 | |
| ø | 90°-93° | | 90°-93° | | |

## TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010
LOT CODE 1789
ASSEMBLED ON WW 19, 2000
IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position indicates "Lead - Free"



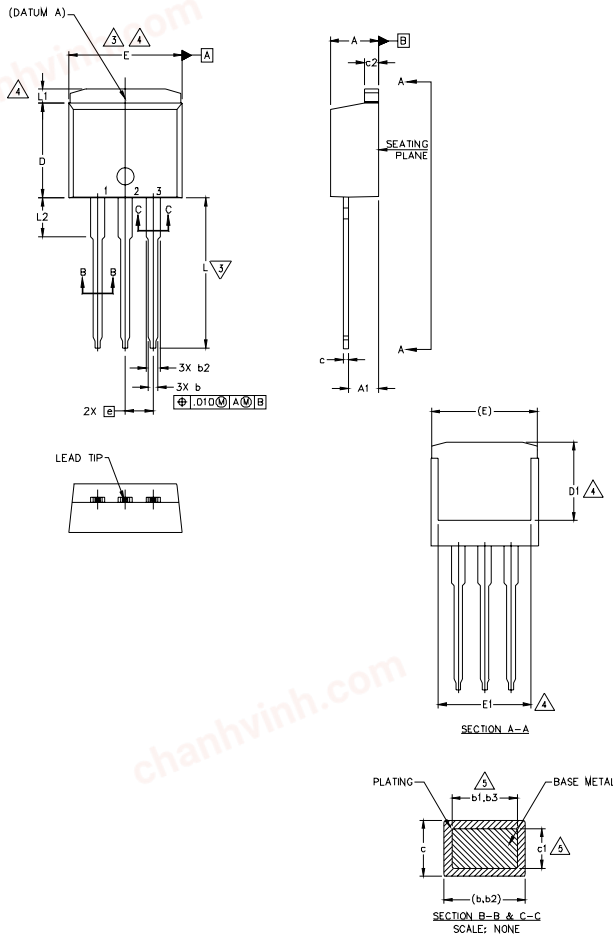

TO-220AB packages are not recommended for Surface Mount Application.

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# TO-262 Package Outline

Dimensions are shown in millimeters (inches)




NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION: INCH.
7. - OUTLINE CONFORM TO JEDEC TO-262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

| SYMBOL | DIMENSIONS | | | | NOTES |
|---|---|---|---|---|---|
| | MILLIMETERS | | INCHES | | |
| | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | .160 | .190 | |
| A1 | 2.03 | 3.02 | .080 | .119 | |
| b | 0.51 | 0.99 | .020 | .039 | |
| b1 | 0.51 | 0.89 | .020 | .035 | 5 |
| b2 | 1.14 | 1.78 | .045 | .070 | |
| b3 | 1.14 | 1.73 | .045 | .068 | 5 |
| c | 0.38 | 0.74 | .015 | .029 | |
| c1 | 0.38 | 0.58 | .015 | .023 | 5 |
| c2 | 1.14 | 1.65 | .045 | .065 | |
| D | 8.38 | 9.65 | .330 | .380 | 3 |
| D1 | 6.86 | - | .270 | - | 4 |
| E | 9.65 | 10.67 | .380 | .420 | 3,4 |
| E1 | 6.22 | - | .245 | | 4 |
| e | 2.54 BSC | | .100 BSC | | |
| L | 13.46 | 14.10 | .530 | .555 | |
| L1 | - | 1.65 | - | .065 | 4 |
| L2 | 3.56 | 3.71 | .140 | .146 | |

LEAD ASSIGNMENTS

HEXFET

1.- GATE
2.- DRAIN
3.- SOURCE
4.- DRAIN

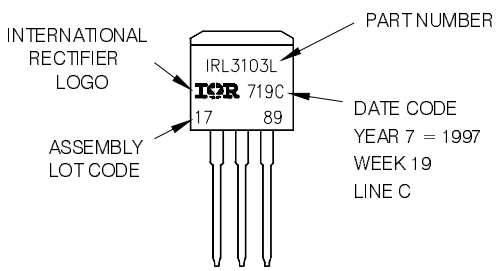
IGBTs, CoPACK

1.- GATE
2.- COLLECTOR
3.- EMITTER
4.- COLLECTOR

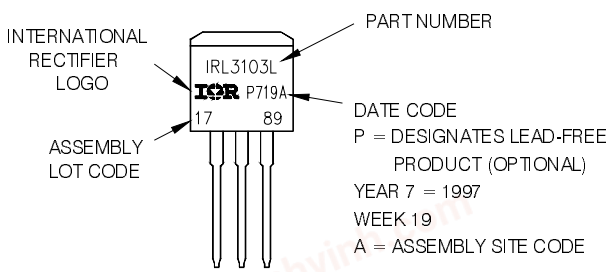
# TO-262 Part Marking Information

EXAMPLE: THIS IS AN IRL3103L
LOT CODE 1789
ASSEMBLED ON WW 19, 1997
IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position indicates "Lead - Free"




OR



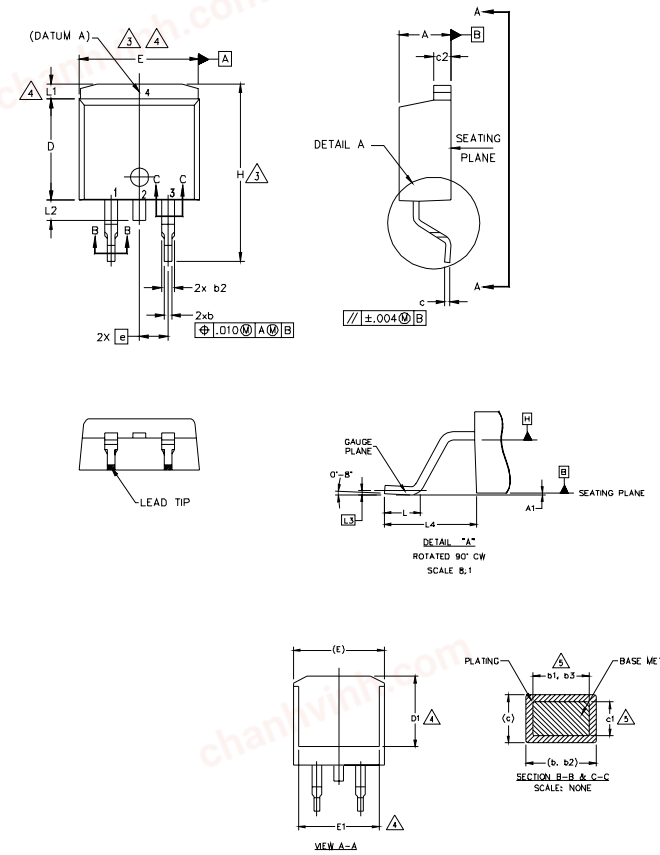
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International
IOR Rectifier

## D²Pak (TO-263AB) Package Outline

Dimensions are shown in millimeters (inches)




NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
7. CONTROLLING DIMENSION: INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263AB.

| SYMBOL | DIMENSIONS | | | | NOTES |
|---|---|---|---|---|---|
| | MILLIMETERS | | INCHES | | |
| | MIN. | MAX. | MIN. | MAX. | |
| A | 4.06 | 4.83 | .160 | .190 | |
| A1 | 0.00 | 0.254 | .000 | .010 | |
| b | 0.51 | 0.99 | .020 | .039 | |
| b1 | 0.51 | 0.89 | .020 | .035 | 5 |
| b2 | 1.14 | 1.78 | .045 | .070 | |
| b3 | 1.14 | 1.73 | .045 | .068 | 5 |
| c | 0.38 | 0.74 | .015 | .029 | |
| c1 | 0.38 | 0.58 | .015 | .023 | 5 |
| c2 | 1.14 | 1.65 | .045 | .065 | |
| D | 8.38 | 9.65 | .330 | .380 | 3 |
| D1 | 6.86 | – | .270 | | 4 |
| E | 9.65 | 10.67 | .380 | .420 | 3,4 |
| E1 | 6.22 | – | .245 | | 4 |
| e | 2.54 BSC | | .100 BSC | | |
| H | 14.61 | 15.88 | .575 | .625 | |
| L | 1.78 | 2.79 | .070 | .110 | |
| L1 | – | 1.65 | – | .066 | 4 |
| L2 | 1.27 | 1.78 | – | .070 | |
| L3 | 0.25 BSC | | .010 BSC | | |
| L4 | 4.78 | 5.28 | .188 | .208 | |

LEAD ASSIGNMENTS

HEXFET

1.– GATE
2, 4.– DRAIN
3.– SOURCE

IGBTs, CoPACK

1.– GATE
2, 4.– COLLECTOR
3.– EMITTER

DIODES

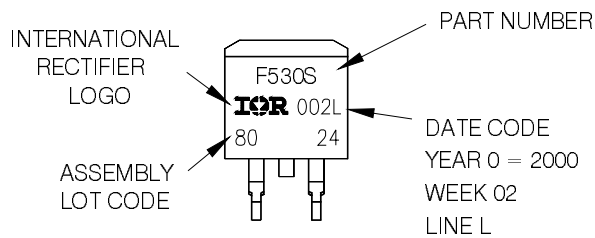
1.– ANODE *
2, 4.– CATHODE
3.– ANODE

* PART DEPENDENT.

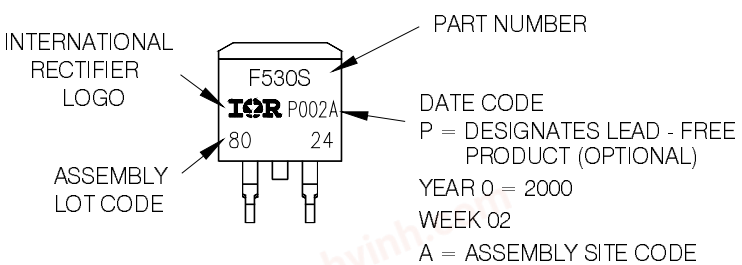
## D²Pak (TO-263AB) Part Marking Information

EXAMPLE: THIS IS AN IRF530S WITH
LOT CODE 8024
ASSEMBLED ON WW 02, 2000
IN THE ASSEMBLY LINE "L"

Note: "P" in assembly line position
indicates "Lead – Free"



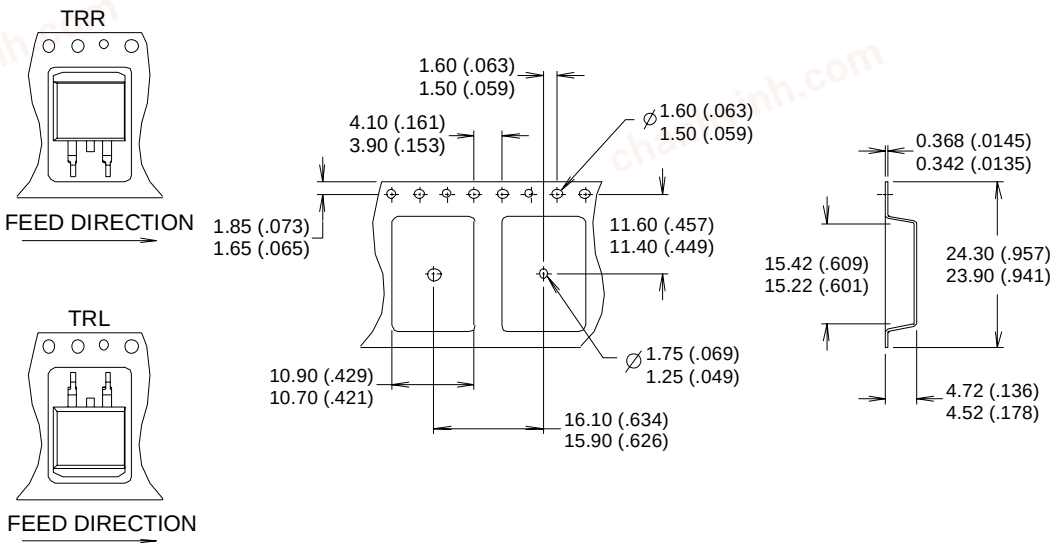

OR

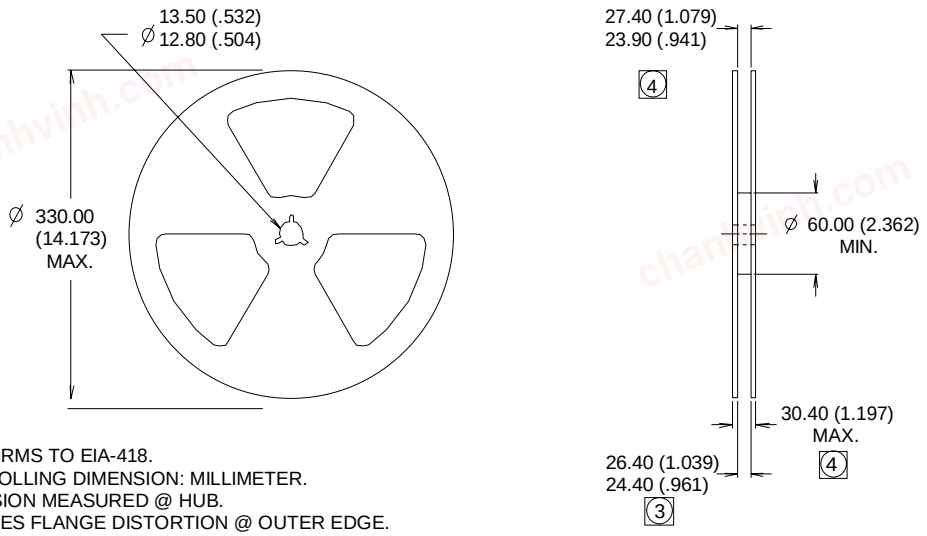


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# D²Pak (TO-263AB) Tape & Reel Information




NOTES :
1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION MEASURED @ HUB.
4. INCLUDES FLANGE DISTORTION @ OUTER EDGE.

Data and specifications subject to change without notice.
This product has been designed and qualified for the Industrial market.
Qualification Standards can be found on IR's Web site.

International
IOR Rectifier

**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7903
Visit us at www.irf.com for sales contact information. 01/06

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Note: For the most current drawings please refer to the IR website at:
http://www.irf.com/package/

chanhvinh.com

chanhvinh.com

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